

Reaction of Co with Ge Studied by *in situ* UHV TEM

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Channel mobility is a major challenge for scaled silicon devices to meet the requirements of sub-45nm device geometries. Ge recently attracted considerable attention due to its high carrier mobility and excellent compatibility with high-k materials.¹ The development of Ge-based complimentary metal-oxide-semiconductor (CMOS) technology requires knowledge about the formation of local metal-semiconductor contact for which metal germanides will be used. Silicides have been extensively investigated,² however formation of germanides on single crystal Ge surface attracted less attention in the past. In this paper, we report the formation and microstructural evolution of epitaxial Co₅Ge₇ phase on a single crystal Ge (001) surface by reactive deposition and solid state reaction in an *in situ* ultra high vacuum (UHV) transmission electron microscope (TEM).

The microscope used for the present work is a modified JEOL-2010 TEM under UHV condition. Atomic Co flux was generated by the electron beam evaporation of high purity Co metal inside the TEM chamber. For reactive deposition, the Ge substrate was maintained at 350°C. For solid state reaction, the deposition of Co on the Ge substrate was at a room temperature, and then the sample was *in situ* annealed at 125°C, 225°C, 300°C and 350°C, respectively. The morphology and structural evolutions of the epitaxial Co₅Ge₇ phase during the reaction of Co with Ge surface in the two experiments were recorded in real-time.

It was found that the reaction and formation mechanisms of cobalt germanide phase and its structural evolution during the reaction are different for two different processes. For the reactive deposition, Co₅Ge₇ phase nucleates on the (001) Ge surface in the form of epitaxial islands with square and rectangular shapes. The morphological evolution of the islands is shown in Fig.1. Two epitaxial orientation relationships between Co₅Ge₇ and (001) Ge surface were observed by *in-situ* electron diffraction and further confirmed by x-ray diffraction for the same sample: Co₅Ge₇ <001>(110) || Ge <100>(001) and Co₅Ge₇ <110>(001) || Ge <100>(001). Anisotropic strain relaxation results in the elongation of the Co₅Ge₇ islands along the Ge <110> direction. For the solid state reaction, a continuous epitaxial Co₅Ge₇ layer on the Ge(001) surface forms at ~300°C, as shown in Fig.2. The epitaxial orientation relationship is identical to that obtained in the reactive deposition at 350°C. By further annealing at 350°C the Co₅Ge₇ film becomes discontinuous with a number of pinholes. This work demonstrates that *in situ* TEM provides a unique way to study the interaction between metal and semiconductor.

References:

[1] SOITEC, "Applied Materials and Soitec Collaborate to Develop Advanced Germanium-on-Insulator Substrates for 45nm and Beyond," <http://www.soitec.com> News and events/Press releases/Company releases/ March 11, 2004.

[2] S. L. Zhang and M. Ostling, *Critical Rev.in Solid State and Mater.Sci.* 28, (2003) 1.

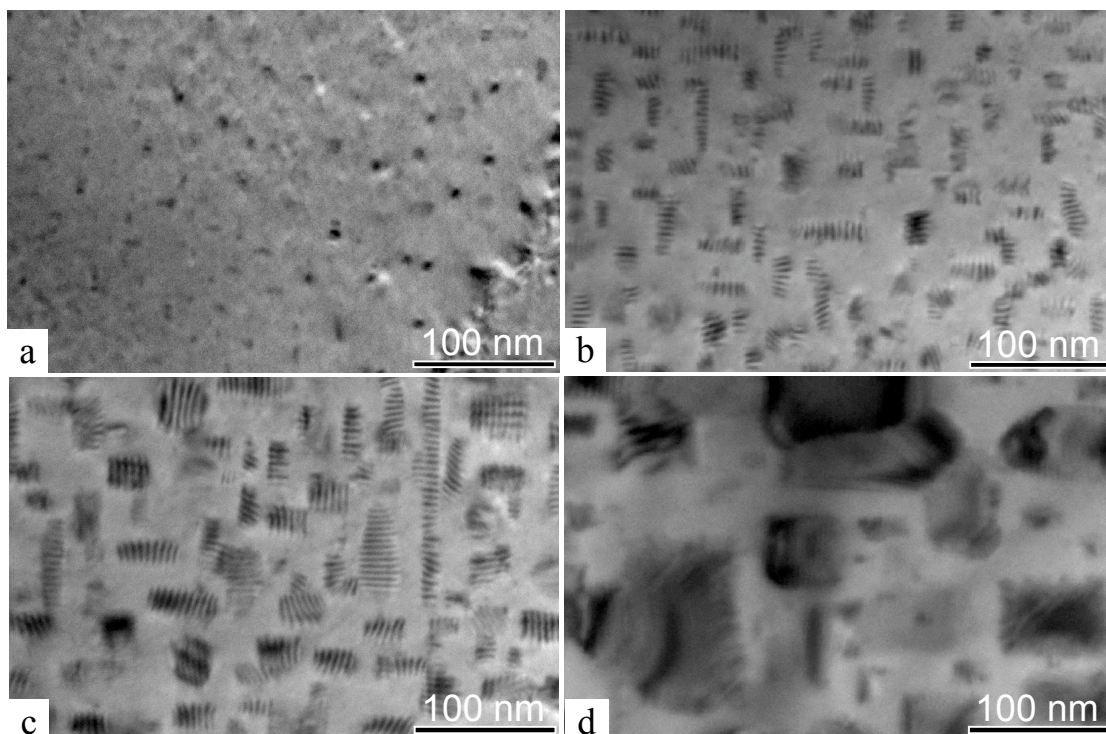


FIG. 1. Time series TEM images showing the morphology evolution of Co deposited on Ge (001) surface (a) 2min, (b) 32min, (c) 61min and (d) 145min during reactive deposition at 350°C.

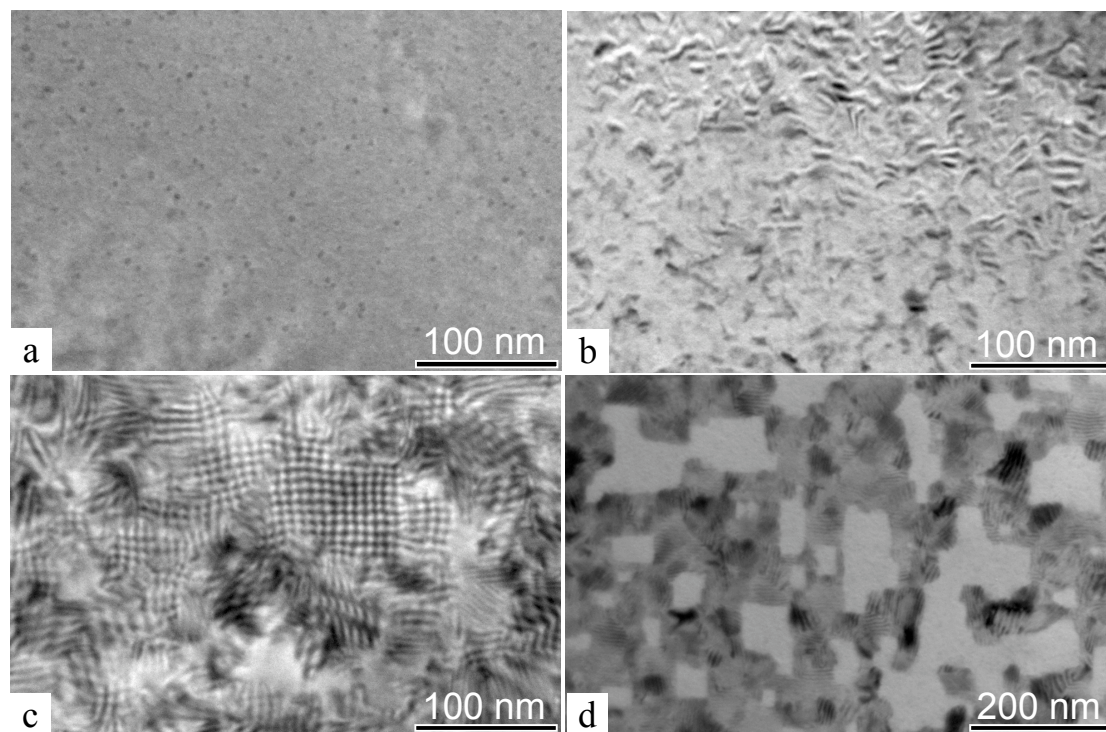


FIG. 2. TEM images showing the morphology of a Co film deposited on the Ge (001) surface and annealed at (a) 125°C, (b) 225°C, (c) 300°C and (d) 350°C.